



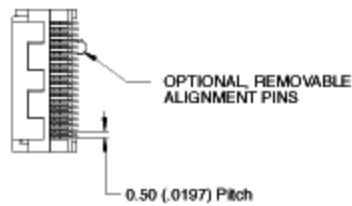
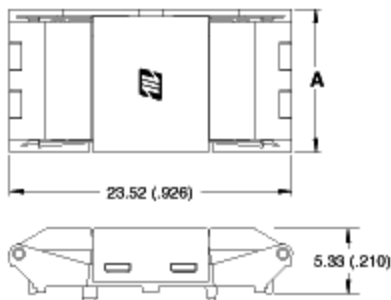
SURFACE MOUNT TSOP SOCKET

FEATURES

For programming, prototyping and test applications, footprint compatible with chip package, zero insertion force, easy to load and and unload, high normal force contacts, positive locking lid design, body,

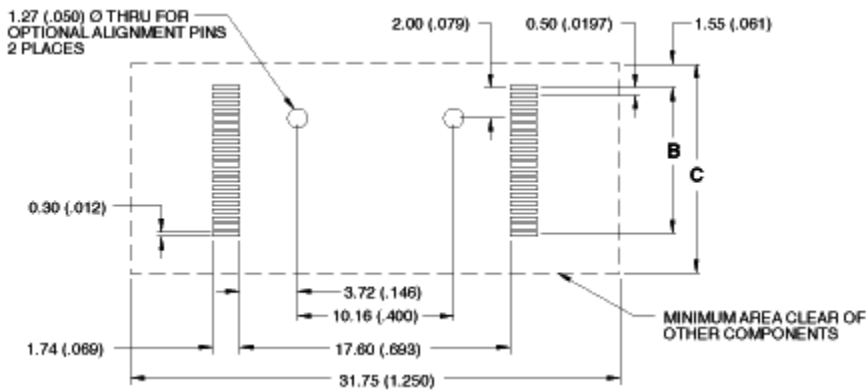
SPECIFICATIONS

body, lid and lock material: Liquid Crystal Polymer, insulation resistance: 500 megohms, dielectric withstanding voltage:250 VAC, terminal material: BeCu with PbSn plating, contact resistance: 30 milliohms max, current rating: 0.5 amp, minimuminsertion/withdrawal cycles: 50, temperature range: -55 degrees C to +105 degrees C, Flammability: 94 V-0



millimeters(inches)

SOCKET LAND-PAD FOOTPRINT



millimeters(inches)

		DIM A		DIM B		DIM C		PART #		STD PKG QTY	
PACKAGE	#LEADS	mm	inches	mm	inches	mm	inches	NO ALIGN	WITH ALIGN	PER TRAY	PE & R
.50mm TSOP	40	11	0.467	9.5	0.374	13	0.536	80020-40-0	80020-40-0	70	250
	48	13	0.545	11	0.453	15	0.615	80020-48-0	80020-48-0	63	250
	56	15	0.624	13	0.531	17	0.694	80020-56-0	80020-56-0	56	250

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